



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-06
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LD29080DT15R	HZGR*NG15FC2	A	SHENZHEN B/E	2015-10-06
Amount		UoM	Unit type	ST ECOPACK Grade
331.30		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	6.085, 6.61, 2.3	3	GULL WING	
Comment	TO-252 DPAK Cu Wire			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HZGR*NG15FC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	2.380	mg	supplier	die	Silicon (Si)	7440-21-3		2.263	mg	950840	6831
				supplier	metallization	Aluminium (Al)	7429-90-5		0.035	mg	14706	106
				supplier	Passivation	Silicon Nitride	12033-89-5		0.010	mg	4202	30
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	7983	57
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	840	6
				supplier	back side metallization	Gold (Au)	7440-57-5		0.005	mg	2101	15
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.016	mg	6723	48
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.030	mg	12605	91
Leadframe	Copper & its alloys	183.855	mg	supplier	alloy	Copper (Cu)	7440-50-8		183.616	mg	998700	554229
				supplier	alloy	Iron (Fe)	7439-89-6		0.085	mg	462	257
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.154	mg	838	465
Soft solder	Solder	2.377	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.270	mg	954985	6852
				supplier	solder	Silver (Ag)	7440-22-4		0.059	mg	24821	178
				supplier	solder	Tin (Sn)	7440-31-5		0.048	mg	20194	145
Bonding wires	Other inorganic materials	0.254	mg	supplier	wire	Copper (Cu)	7440-50-8		0.254	mg	1000000	767
				supplier	mold compound	Silica, vitreous	60676-86-0		123.715	mg	874997	373423
				supplier	mold compound	Tetramethyl-biphenyl-diyl-bis oxymethylene-b	EC 413-900-7		5.656	mg	40003	17072
				supplier	mold compound	Epoxy Resin	25068-38-6		4.242	mg	30002	12804
				supplier	mold compound	phenol resin	29690-82-2		7.069	mg	49997	21337
Encapsulation	Other Organic Materials	141.389	mg	supplier	mold compound	Carbon black	1333-86-4		0.707	mg	5000	2134
				supplier	mold compound	Tin (Sn)	7440-31-5		1.045	mg	1000000	3154
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3154